This GIDEP PCN is to announce the transfer of wafer fabrication site for the following International Rectifier Part No.

<table>
<thead>
<tr>
<th>Part (jedec #)</th>
<th>Description</th>
<th>Package</th>
</tr>
</thead>
<tbody>
<tr>
<td>IRF9140</td>
<td>-100V, P-Channel, Hi-Rel MOSFET, TO-204AA package</td>
<td></td>
</tr>
<tr>
<td>IRFM9140 [2N7236]</td>
<td>-100V, P-Channel, Hi-Rel MOSFET, TO-254AA package</td>
<td></td>
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<tr>
<td>IRFN9140 [2N7236U]</td>
<td>-100V, P-Channel, Hi-Rel MOSFET, SMD-1 package</td>
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<tr>
<td>IRFY9140, IRFY9140M</td>
<td>-100V, P-Channel, Hi-Rel MOSFET, TO-257AA package</td>
<td></td>
</tr>
<tr>
<td>IRFY9140C, IRFY9140CM</td>
<td>-100V, P-Channel, Hi-Rel MOSFET, TO-257AA package (glass seal)</td>
<td></td>
</tr>
</tbody>
</table>

Change:
Transfer (Vishay Intertechnology) die fabrication from International Rectifier (FAB 1) in Temecula, CA to Tower Semiconductor in Migdal Haemak, Israel.

Impact of Change:
There will be no impact to the fit, form, function, quality or reliability of the parts. There will be no change to the datasheet parameters.